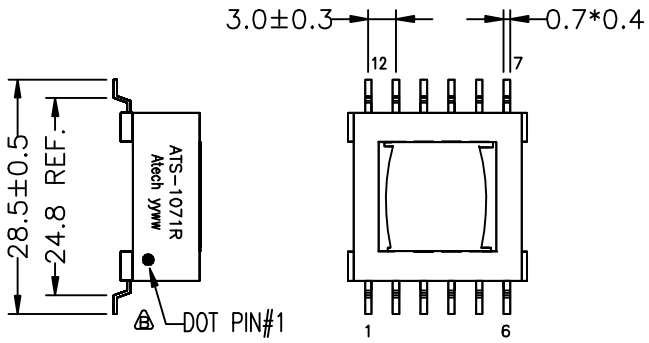
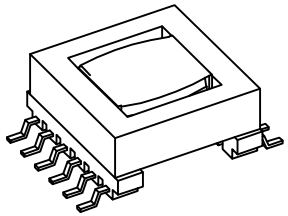
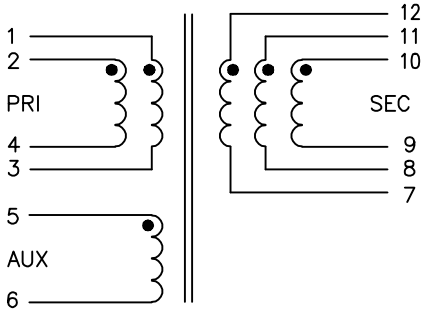
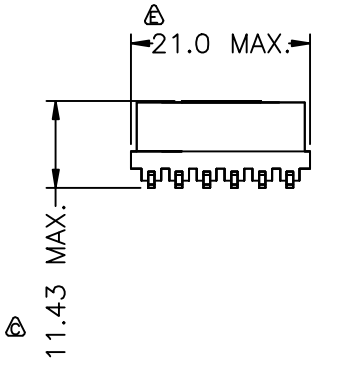
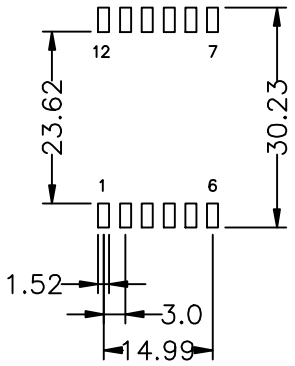





SUGGESTED PAD LAYOUT

## ELECTRICAL CHARACTERISTICS:

1. D.C.R : (1−2, 3−4 SHORT) 1−3 = 69mΩ MAX.
   12−7(10−11−12, 7−8−9 SHORT) = 15mΩ MAX. 5−6 = 195mΩ MAX.
   1−3 = 100mΩ MAX. 2−4 = 120mΩ MAX. 10−9 = 35mΩ MAX.
   11−8 = 35mΩ MAX. 12−7 = 35mΩ MAX.

2. INDUCTANCE (@250kHz, 0.7Vrms) : 1−3 = 42uH ±10%(1−2, 3−4 SHORT)
   (@250kHz, 0.7Vrms, DC Bias 2.6A) : 1−3 = 37.8uH MIN.(1−2,3−4 SHORT)

3. LEAKAGE INDUCTANCE(@250kHz,0.7Vrms)
   (1−2, 3−4, 5−6, 7−8−9−10−11−12 SHORT)1−3 = 0.545uH MAX.

4. TURN RATIO (@250kHz,0.7Vrms)
   1−3 : 2−4 = 1 ±2%, 1−3 : 5−6 = 3.03 ±2%, 1−3 : 10−9 = 3.03 ±2%
   1−3 : 11−8 = 3.03 ±2%, 1−3 : 12−7 = 3.03 ±2%

5. HI−POT (@1500VAC, 1mA, 2SEC. 1−2, 3−4, 7−8−9, 10−11−12 SHORT) 5−1, 5−7

6. OUTPUT : PIN 12−7, 11−8, 10−7 = 12V , 2.5A

7. OPERATING TEMPERATURE RANGE : −40°C~+125°C

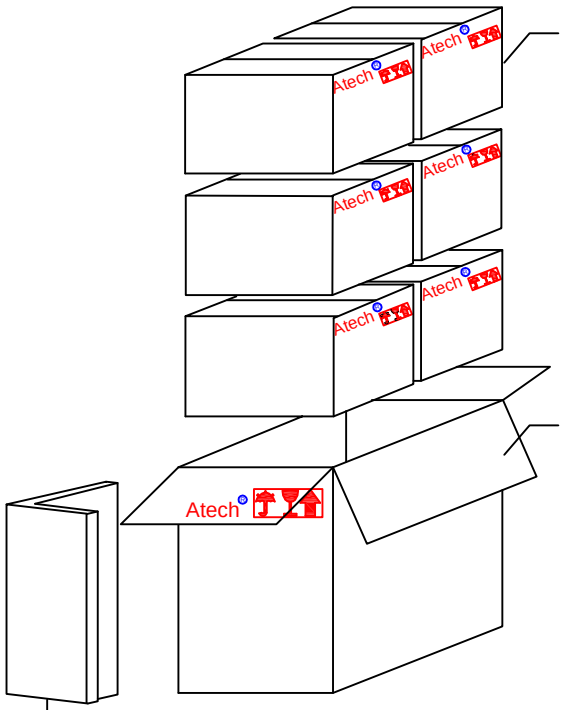
8. RoHS COMPLIANT

| NO: | DESCRIPTION | DATE | BY | CHK | APPD |
|---|---|---|---|---|---|
| E | CHANGE DIM. | 06/20/2018 | SHIRLEY | BETTY | BETTY |
| D | CHANGE ELECTRICAL CHARACTERISTICS | 01/27/2014 | SHIRLEY | BETTY | BETTY |
| C | CHANGE DIM. | 02/23/2012 | SHIRLEY | BETTY | BETTY |
| | RELEASE | 08/16/2011 | SHIRLEY | BETTY | BETTY |

REVISIONS

AOEM.

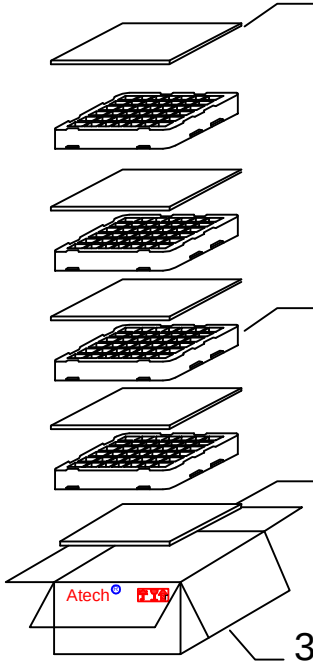
| | |
|---|---|
| TITLE | FLYBACK TRANSFORMER |
| DWG. NO. | ATS-1071R |
| UNITS: | M/M |
| SAFETY | |
| SHEET | 1 OF 1 |
| DATE | 08/16/11 |
| P/N: | |
| DRAW | SHIRLEY |




3212320105
(INNER BOX)
(PK-044)*6PCS

3214224106
(PK-058)*1PCS
(CARTON)

外箱4棱角处加"护角"保护




3240300009 or 3240300001
PK-045*5PCS

3231221901 * 4PCS
每盘脆盘上放一块珍珠棉

纸箱底部放一块珍珠棉3240300009

3212320105
CARTON:PK-044*1PCS
1 CARTON: 160 PCS

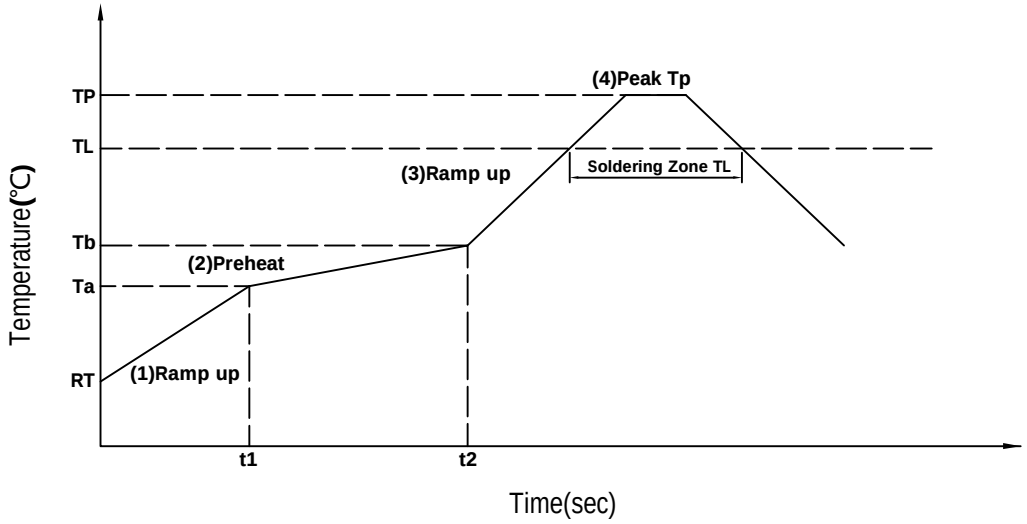
ONE TRAY: 40 PCS

ONE BOX: 4PCS TRAYS * 5PCS 3240300009 or (3240300001)

ONE CARTON: 6 PCS 3212320105 960PCS

| | | | | | | | |
|---|---|---|---|---|---|---|---|
| | | | | | | AOEM | TITLE: PACKING |
| | | | | | | | DWG. NO: 968SE66500 |
| | RELEASE | 07/01/2016 | Wang | Wang | Dai | UNITS: M/M | SAFETY: |
| NO: | DESCRIPTEON | DATE | BY | CHK | APPD | | SHEET 1 OF 1 |
| | REVISIONS | | | | | DATE: 07/01/2016 | P/N: DRAW: 汪诗梅 |

# Pb-free Soldering IR Reflow(SMD)




1,MSL Grade: 1 Level 2,Floor life: 2years 3,Condition:≤30℃ RH 85%

2,Form-1(Reference JEDEC J-STD-020D Table 5-2)

| IR reflow profile | | Pb-free |
|---|---|---|
| step# | Profile Feature | Condition/Duration |
| step1 | Ramp-up rate | 3℃**/second max** |
| step2 | Preheat:150℃**-200**℃**(Ta-Tb)** | **t1-t2:60-120seconds** |
| step3 | Ramp-up rate(TL to Tp) | 3℃**/second max** |
| | Temperature maintained above 217℃ | 60-150seconds |
| step4 | Peak temperature(Tp) | 260+0/-5℃ |
| | Time within 5℃ of actual peak temperature | 30seconds max |
| Ramp-down rate(Tp to TL) | | 6℃**/second max** |

3,Form-2(Reference JEDEC J-STD-020D Table 4-2)

| Package Thickness | Volume $mm^3$ <350 | Volume $mm^3$ 350-2000 | Volume $mm^3$ >2000 |
|---|---|---|---|
| <1.6mm | 260+0/-5℃ | 260+0/-5℃ | 260+0/-5℃ |
| 1.6mm-2.5mm | 260+0/-5℃ | 250+0/-5℃ | 245+0/-5℃ |
| >2.5mm | 250+0/-5℃ | 245+0/-5℃ | 245+0/-5℃ |